

FEATURES

The plastic package carries Underwriters Laboratory

Flammability Classification 94V-0

For surface mounted applications

Super fast switching for high efficiency

Low reverse leakage

Built-in strain relief, ideal for automated placement

High forward surge current capability

High temperature soldering guaranteed:

260°C/10 seconds at terminals

Glass passivated chip junction

MECHANICAL DATA

Case: JEDEC DO-214AB molded plastic body over passivated chip

Terminals: Solder plated, solderable per MIL-STD-750,

Method 2026

Polarity: Color band denotes cathode end

Mounting Position: Any

Weight: 0.007 ounce, 0.25 grams

0.245(6.22) 0.280(7.11) 0.103(2.62) 0.060(1.52) 0.030(0.76) 0.008(0.203)MAX

SMC / DO-214AB

Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

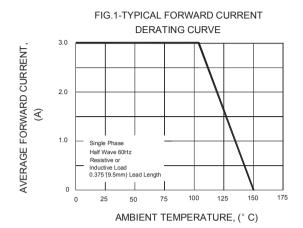
Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

	SYMBOLS	ES3M	UNIT
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	1000	Volts
Maximum RMS Voltage	V_{RMS}	700	Volts
Maximum DC Blocking Voltage	$V_{ m DC}$	1000	Volts
Maximum Average Forward Rectified Current At T _L =105 (NOTE 1)	$I_{(AV)}$	3.0	Amps
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	100	Amps
Maximum Instantaneous Forward Voltage at 3.	0A V _F	1.7	Volts
Maximum DC Reverse Current T _A = 2	25 I _R	10	μА
at rated DC Blocking Voltage at T _A	1 _R	200	PΑ
$\label{eq:maximum} \begin{array}{l} \text{Maximum Reverse Recovery Time} \\ \text{Test conditions } I_F \!=\! 0.5 A, I_R \!=\! 1.0 A, I_{RR} \!=\! 0.25 A \end{array}$	t _{rr}	75	nS
Typical Junction Capacitance (Measured at 1.0MHz and applied reverse voltage of	4.0V) C _J	50	pF
T-mi1 Thermal Desistance (Nets 1)	R _{TA}	55	/\
Typical Thermal Resistance (Note 1)	R _{UL}	17	/W
Operating Junction Temperature	T_{J}	(-55 to +150)	
Storage Temperature Range	T_{STG}	(-55 to +150)	

1. Thermal resistance from Junction to ambient and from junction to lead mounted on P.C.B. with 0.3×0.3 ! (8.0 \times 8.0mm) copper pad areas.









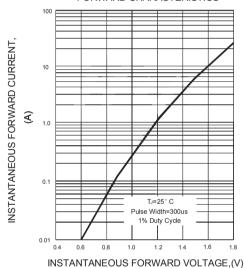


FIG.5-TYPICAL JUNCTION CAPACITANCE

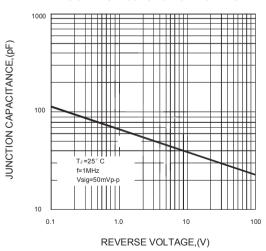


FIG.2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

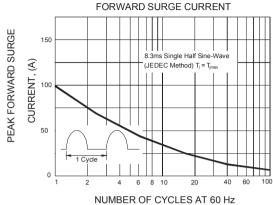
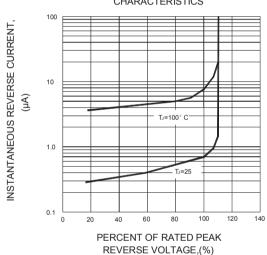
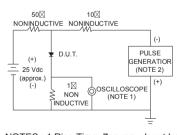
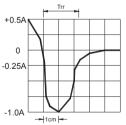


FIG.4-TYPICAL REVERSE **CHARACTERISTICS**



F1G.6-TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTIC





NOTES: 1.Rise Time=7ns max. Input Impedance= 1 megohm. 22pF

2.Rise time=10ns max. Source Impedance= 50 ohms

SET TIME BASE FOR 50/100ns/cm

